LRDR9G91-2I

PCIe5.0 x8 2*DDR5 CXL Adapter(Montage Based)



Product Features

-Support PCIe 5.0 (32GT/s) x8 interface;
-Comply with CXL2.0 specification;
-Comply with JEDEC DDR5 specifications;
-Only supports DDR5 RDIMM.

Product Description

LRDR9G91-2I is a PCIe5.0 x8 to dual-slot DDR5 memory expansion card designed by Linkreal Co., Ltd. based on Montage main control solution. Designed to meet the needs of high-performance computing and data center applications, the product provides exceptional performance and reliability. This memory expansion card uses the PCIe 5.0 x8 interface and supports data transfer rates up to 32GT/s, providing the system with powerful bandwidth and fast data access capabilities. At the same time, the LRDR9G91-2I complies with the CXL 2.0 specification, ensuring future scalability and interoperability. LRDR9G91-2I complies with the JEDEC DDR5 specification and is compatible with the latest generation of DDR5 memory, providing advanced memory technology support. The highest rate it supports is DDR5-5600*2 RDIMM, providing users with excellent memory performance and response speed.

In addition, the LRDR9G91-2I adopts a dual-slot design that can accommodate two DDR5 memory modules at the same time, maximizing system memory capacity and performance. Its well-designed cooling system and stable power supply ensure stability and reliability under high load and long-term operation. In summary, the LRDR9G91-2I memory expansion card is a powerful, stable and reliable solution for computing and data center environments that require large memory capacity and high-speed data access.

Technical Specifications

Model	LRDR9G91-2I
Controller	Montage
Bus Type	PCIe5.0（32GT/s）x8
Bracket Height	Low Profile & Full Height
Power consumption (min)	11.184W
Power consumption (max)	12.504W
CPU	Requires 4th generation Scalable Intel® Xeon® processors and above
Operating System Support	* Windows 10/11 * Deepin 15.11/20/20.6/20.9 * Galaxy Unicorn V10 * Galaxy Unicorn V10 SP1 * NeoKylin 7.6 * RHEL/CentOS 7.3/7.6/7.9/8.2/8.3 * SUSE 15.4 * ZTE New Fulcrum 5.0.5/3.2.2 * Asianux Server V7.0 * Tongxin UOS 20 * Ubuntu 16.04.3/18.04.5 * Ubuntu 20.04.1/22.04.2

Memory Specifications

Memory Configuration	Maximum quantity	Slot location	Maximum Capacity per Stick	Total Maximum Capacity
1-Rank	1	Speed 1DPC	128GB	128GB (128GB x 1)
2-Rank	2	Speed 1DPC, Speed 2DPC	128GB	256GB (128GB x 2)

Working parameters

Operating Temperature	0℃ to 70℃ (32℉ to 158℉)
Storage Temperature	0℃ to 70℃ (32℉ to 158℉)
Storage Humidity	Maximum: 90% non-condensing relative humidity at 35 ℃
Certification	FCC, CE, RoHS

Physical properties

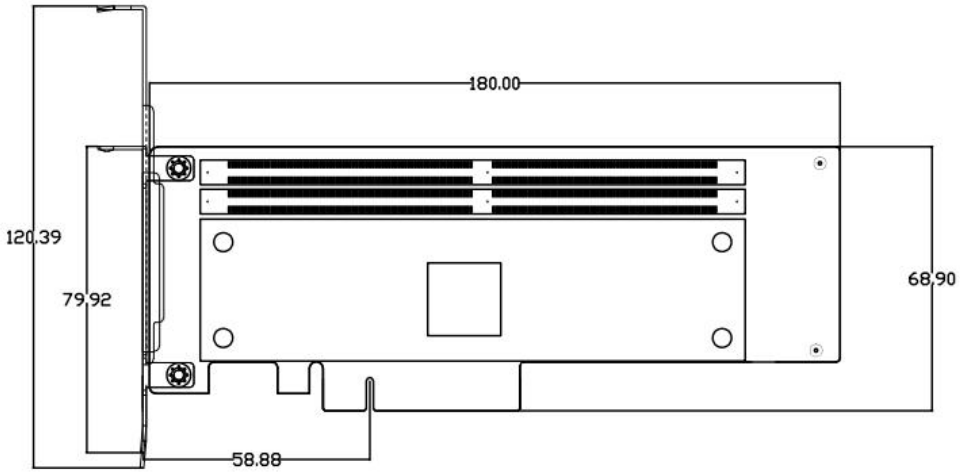
PCB size(unit:mm)	180*68.9*1.6
Package size (unit: mm)	222*147*28

Packing list

Baffle specifications	Full Height(installed) and Low Profile
Network card	*1
Product warranty card	*1
Packing	Carton and Static bag

* Product appearance and specifications are subject to change without nonce.

Dimensions(unit:mm)



Linkreal Co., Ltd.
14F T10 Bldg., Sino-Ocean New World, Longcheng Street, Longgang District Shenzhen China 518172
(+86)755-84507909
service@lr-link.com
www.lr-link.com